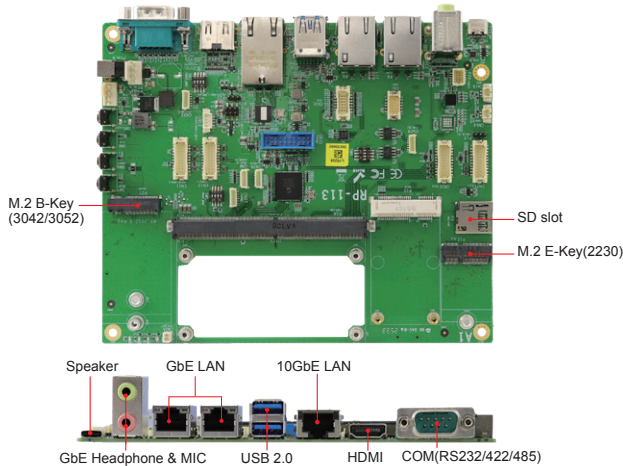




Features

- For SMARC™ V2.2 modules
- Supports 19V~24V DC-in, reset, power, RTC function
- Supports 10 Gigabit LAN, Gigabit LAN, audio, USB 3.0, COM (RS232/422/485)
- With MicroSD socket, Mini PCIe with USB, SIM socket on board
- With M.2 E-Key 2230 for Wi-Fi/BT, M.2 B-Key 3042/3052 for 4G/5G
- Supports 2x CAN transceiver, TTL interface, LVDS, HDMI, MIPI-CSI camera

Specifications

Form Factor	Carrier Board Compliant with SMARC™ 2.2
Edge I/O	1x RJ45 10GbE 2x RJ45 GbE 2x USB 3.0 Type A 1x USB 2.0 Type C for firmware download 1x HDMI 1x COM (RS232/422/485) 1x SD Slot 2x Nano SIM slot 1x DC-in jack (19V~24V) 1x Headphone & MIC
Internal I/O	2x CAN bus 2.0B 2x CAN bus via SPI 2x USB3.0 (pin header) 1x Fan (4-wire) 1x 3.3V/5V/12V back light wafer 1x MIPI display power (3.3V/5V) 1x MIPI-DSI/LVDS 4-lanes 1x LVDS 4-lanes 1x MIPI-CSI2 2-lanes 1x MIPI-CSI2 4-lanes 12x GPIOs (1.8V) 2x RS232 (RX/TX, pin header) 1x I²C (capacitive touch pin header) 1x I²S 1x QSPI (pin header) 1x mPCIe slot (PCIe, USB2.0, PCM) 1x M.2 E-Key 2230 slot (PCIe, SDIO, UART, USB 2.0) 1x M.2 B-Key 3042/3052 slot (USB 3.0 only) 1x Speaker R and L 1x RTC battery 4x LEDs
Jumpers, Switch & Buttons	1x Boot select switch 1x Power button 1x Reset button 1x Sleep button 1x LID button
Power Input	19V~24V DC-in
Dimensions	170mm x 140mm (6.7" x 5.5")
Environment	Humidity: 0% to 90% RH at 60° C (non-condensing)

Operating Temperature	-40°C ~ 85°C (-40°F ~ 185°F)
OS Support	Based on the CPU module
Certification	CE/FCC Class B

Ordering Information

RP-113	RISC Carrier Board for NXP SMARC™ 2.2 modules, 19V~24V DC-in, 170mmx140mm, 2x CAN, Mini PCIe with USB, 2x USB header, 1x I²C header, DSI/LVDS, Speaker out, Line in/ Line out, MIPI CSI, 12x GPIO, 2x RS232, 1x RS232/422/485, VDDIO=1.8V
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Dimensions

